IN THE CLAIMS

1. (Currently Amended) A method, comprising:

heating a stamper and a resist film;

imprinting the stamper into the resist film;

separating the stamper from the resist film before ~~there is any substantial cooling of~~ the resist film is cooled below approximately a glass transition temperature of the resist film; and

cooling the resist film below the glass transition temperature after the separating.

2. (Currently Amended) The method of claim 1, wherein the stamper and the resist film are heated to a temperature at least that of ~~a~~ the glass transition temperature of the resist film.

3. (Original) The method of claim 1, wherein imprinting the stamper into the resist film comprises imprinting the stamper into the resist film to produce a pattern of trenches areas and plateau areas.

4. (Original) The method of claim 1, further comprising disposing the resist film above a base structure prior to the heating, wherein the base structure comprises a substrate.

5. (Original) The method of claim 4, further comprising selectively removing the resist film to form a pattern of areas above the base structure that do not have the resist film thereon.

6. (Original) The method of claim 5, further comprising disposing a magnetic layer above the base structure in the areas that do not have the resist film.

7. (Original) The method of claim 5, further comprising etching the base structure using the patterned resist film.

8. (Original) The method of claim 1, wherein the resist film comprises a single resist layer.

9. (Original) The method of claim 1, wherein the resist film comprises a plurality of resist layers.

10. (Previously Presented) The method of claim 2, further comprising preheating the resist film to the temperature before heating the stamper.

11. (Original) The method of claim 1, wherein heating the stamper and the resist film comprises separately heating the stamper and the resist film.

12. (Currently Amended) The method of claim 11, wherein the stamper and the resist film are separately heated to an imprint temperature at least that of ~~a~~ the glass transition temperature of the resist film.

13. (Original) The method of claim 12, further comprising placing the resist film in close proximity to the stamper while the resist film is approximately at the imprint temperature.

14. (Currently Amended) The method of claim 11, wherein the stamper is heated to a first temperature at least that of ~~a~~ the glass transition temperature of the resist film and wherein the resist film is separately heated to a second temperature below that of the first temperature.

15. (Original) The method of claim 14, further comprising further heating the resist film to the first temperature.

16. (Currently Amended) The method of claim 11, wherein the stamper is heated to a first temperature at least that of ~~a~~ the glass transition temperature of the resist film and wherein the resist film is separately heated to a second temperature above that of the first temperature.

17. (Canceled)

18. (Previously Presented) The method of claim 21, further comprising disposing the resist film above a base structure prior to the heating, wherein the base structure comprises a substrate.

19. (Previously Presented) The method of claim 21, further comprising:

selectively etching the resist film to form a pattern of areas above the base structure that do not have the resist film thereon; and

disposing a magnetic layer above the base structure in the areas that do not have the resist film.

20. (Canceled)

21. (Previously Presented) A method, comprising:

heating a stamper and a resist film to a first temperature at least that of a transition temperature of the resist film, wherein the resist film comprises a plurality of resist layers;

imprinting the stamper into the resist film;

cooling the resist film to a second temperature above room temperature; and

separating the stamper from the resist film.

22. (Previously Presented) The method of claim 1, wherein the resist film comprises a thermosetting material.

23. (Previously Presented) The method of claim 7, further comprising removing the resist film, wherein a pattern of raised zones and recessed zones is formed in the base structure and wherein the method further comprising depositing a continuous film on the pattern of raised zones and recessed zones.

24. (Previously Presented) The method of claim 23, wherein the resist film comprises a thermosetting material.